

#### 3.0x2.0mm SURFACE MOUNT LED LAMP

Blue

PRELIMINARY SPEC



**ATTENTION** OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE

**DEVICES** 

Part Number: KA-3020APBS-Z

#### **Features** Description

- 3.0MM X 2.0MM, 1.4MM HIGH, ONLY MINIMUM
- SPACE REQUIRED.
- SUITABLE FOR COMPACT OPTOELECTRONIC APPLICATIONS.
- LOW POWER CONSUMPTION.
- PACKAGE: 2000PCS/REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

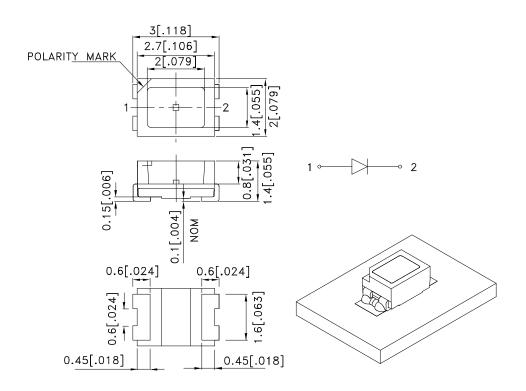
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

### **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





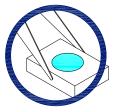
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#### **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

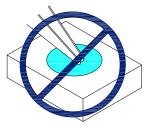
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

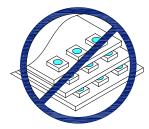


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

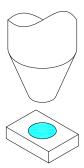




3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratch the silicone lens or damage the internal circuitry.



4. During surface-mounting, the pickup capillary diameter should be larger than the silicone lens to insure the capillary does not scratch or damage the lens.



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#### **Selection Guide**

Part No.	Dice	Lens Type Iv (mcd) [2] @ 20mA		,	Viewing Angle [1]
		7,1	Min.	Тур.	201/2
KA-3020APBS-Z	Blue (InGaN)	WATER CLEAR	110	280	120°

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	458		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue	465		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	22		nm	IF=20mA
С	Capacitance	Blue	110		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue	3.2	3.7	V	IF=20mA
lR	Reverse Current	Blue		10	uA	V <sub>R</sub> =5V

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

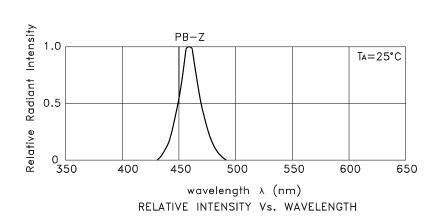
#### Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units	
Power dissipation	111	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	100	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

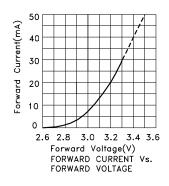
### Note:

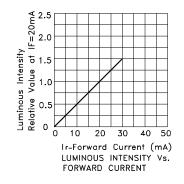
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

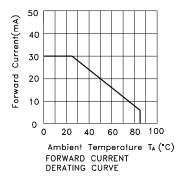
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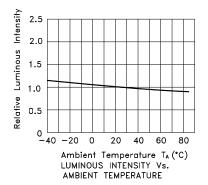


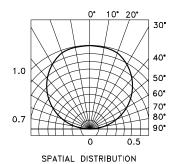
Blue KA-3020APBS-Z









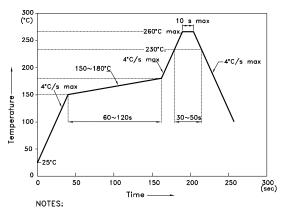


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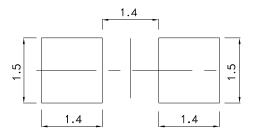
Reflow Soldering Profile For Lead-free SMT Process.



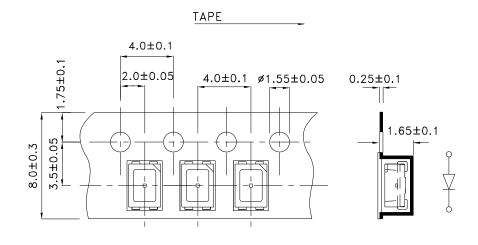
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
   3.Number of reflow process shall be 2 times or less.

### **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



### **Tape Specifications** (Units: mm)



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